CD54/74AC623
CD54/74ACT623

FUNCTIONAL DIAGRAM

Octal-Bus Transceiver, 3-State, Non-Inverting

Type Features:
- Buffered inputs
- Typical propagation delay:
  4.5 ns @ V_{CC} = 5 V, T_A = 25°C, C_L = 50 pF

The RCA CD54/74AC623 and CD54/74ACT623 octal-bus transceivers use the RCA ADVANCED CMOS technology. They are non-inverting, 3-state, bidirectional transceiver-buffers that allow for two-way transmission from "A" bus to "B" bus or "B" bus to "A" bus, depending on the logic levels of the Output Enable (OE_{AB}, $\overline{OE}_{BA}$) inputs.

The dual Output Enable provision gives these devices the capability to store data by simultaneously enabling OE_{AB} and $\overline{OE}_{BA}$. Each output reinforces its input under these conditions, and when all other data sources to the bus lines are at high-impedance, both sets of bus lines will remain in their last states.

The CD74AC623 is supplied in 20-lead dual-in-line plastic packages (E suffix) and in 20-lead small-outline packages (M, M96, and NSR suffixes). The CD74ACT623 is supplied in 20-lead small-outline packages (M96 suffix). Both package types are operable over the following temperature ranges: Commercial (0 to 70°C); Industrial (−40 to +85°C); and Extended Industrial/Military (−55 to +125°C).

The CD54AC623 and CD54ACT623, available in chip form (H suffix), are operable over the -55 to +125°C temperature range.

Family Features:
- Exceeds 2-kV ESD Protection - MIL-STD-883, Method 3015
- SCR-Latchup-resistant CMOS process and circuit design
- Speed of bipolar FAST*/AS/S with significantly reduced power consumption
- Balanced propagation delays
- AC types feature 1.5-V to 5.5-V operation and balanced noise immunity at 30% of the supply
- ± 24-mA output drive current
  - Fanout to 15 FAST* ICs
  - Drives 50-ohm transmission lines

*FAST is a Registered Trademark of Fairchild Semiconductor Corp.

TRUTH TABLE

OUTPUT ENABLE INPUTS		OPERATION
$\overline{OE}_{BA}$	OE_{AB}	
L	L	B DATA TO A BUS
H	H	A DATA TO B BUS
H	L	ISOLATION
L	H	B DATA TO A BUS, A DATA TO B BUS

H = High level, L = Low level

Note: To prevent excess currents in the High-Z (isolation) modes, all I/O terminals should be terminated with 10 kΩ to 1 MΩ resistors.

This data sheet is applicable to the CD74AC623 and CD54/74ACT623. The CD54AC623 was not acquired from Harris Semiconductor.

MAXIMUM RATINGS, *Absolute-Maximum Values:*

DC SUPPLY-VOLTAGE (V_{CC}) . . . . –0.5 to 6 V

DC INPUT DIODE CURRENT, I_{IK} (for V_I < –0.5 V or V_I > V_{CC} + 0.5 V) . . . . ±20 mA

DC OUTPUT DIODE CURRENT, I_{OK} (for V_O < –0.5 V or V_O > V_{CC} + 0.5 V) . . . . ±50 mA

DC OUTPUT SOURCE OR SINK CURRENT per Output Pin, I_O (for V_O > –0.5 V or V_O < V_{CC} + 0.5 V) . . . . ±50 mA

DC V_{CC} or GROUND CURRENT (I_{CC} or I_{GND}) . . . . ±100 mA*

POWER DISSIPATION PER PACKAGE (P_D):

    For T_A = –55 to +100°C (PACKAGE TYPE E) . . . . 500 mW

    For T_A = +100 to +125°C (PACKAGE TYPE E) . . . . Derate Linearly at 8 mW/°C to 300 mW

    For T_A = –55 to +70°C (PACKAGE TYPE M) . . . . 400 mW

    For T_A = +70 to +125°C (PACKAGE TYPE M) . . . . Derate Linearly at 6 mW/°C to 70 mW

OPERATING-TEMPERATURE RANGE (T_A) . . . . –55 to +125°C

STORAGE TEMPERATURE (T_{stg}) . . . . –65 to +150°C

LEAD TEMPERATURE (DURING SOLDERING):

    At distance 1/16 ± 1/32 in. (1.59 ± 0.79 mm) from case for 10 s maximum . . . . +265°C

    Unit inserted into PC board min. thickness 1/16 in. (1.59 mm) with solder contacting lead tips only . . . . +300°C

*For up to 4 outputs per device; add ± 25 mA for each additional output.

RECOMMENDED OPERATING CONDITIONS:

For maximum reliability, normal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range, V_{CC}*:			
(For T_A = Full Package-Temperature Range)			
AC Types	1.5	5.5	V
ACT Types	4.5	5.5	V
DC Input or Output Voltage, V_I, V_O	0	V_{CC}	V
Operating Temperature, T_A	–55	+125	°C
Input Rise and Fall Slew Rate, dt/dv			
at 1.5 V to 3 V (AC Types)	0	50	ns/V
at 3.6 V to 5.5 V (AC Types)	0	20	ns/V
at 4.5 V to 5.5 V (ACT Types)	0	10	ns/V

*Unless otherwise specified, all voltages are referenced to ground.

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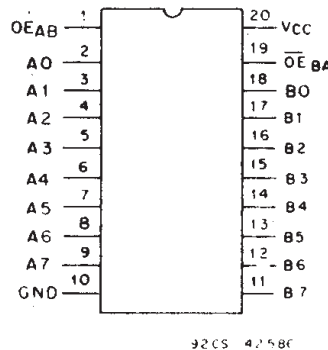
TERMINAL ASSIGNMENT

CD54/74AC623
CD54/74ACT623

STATIC ELECTRICAL CHARACTERISTICS: AC Series

CHARACTERISTICS	TEST CONDITIONS		V_{CC} (V)	AMBIENT TEMPERATURE (T_A) - °C						UNITS
				+25		−40 to +85		−55 to +125		
	V_I (V)	I_O (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage V_{IH}			1.5	1.2	—	1.2	—	1.2	—	V
			3	2.1	—	2.1	—	2.1	—	
			5.5	3.85	—	3.85	—	3.85	—	
Low-Level Input Voltage V_{IL}			1.5	—	0.3	—	0.3	—	0.3	V
			3	—	0.9	—	0.9	—	0.9	
			5.5	—	1.65	—	1.65	—	1.65	
High-Level Output Voltage V_{OH}	V_{IH} or V_{IL}	−0.05	1.5	1.4	—	1.4	—	1.4	—	V
		−0.05	3	2.9	—	2.9	—	2.9	—	
		−0.05	4.5	4.4	—	4.4	—	4.4	—	
		−4	3	2.58	—	2.48	—	2.4	—	
		−24	4.5	3.94	—	3.8	—	3.7	—	
	#, * {	−75	5.5	—	—	3.85	—	—	—	
		−50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage V_{OL}	V_{IH} or V_{IL}	0.05	1.5	—	0.1	—	0.1	—	0.1	V
		0.05	3	—	0.1	—	0.1	—	0.1	
		0.05	4.5	—	0.1	—	0.1	—	0.1	
		12	3	—	0.36	—	0.44	—	0.5	
		24	4.5	—	0.36	—	0.44	—	0.5	
	#, * {	75	5.5	—	—	—	1.65	—	—	
		50	5.5	—	—	—	—	—	1.65	
Input Leakage Current I_I	V_{CC} or GND		5.5	—	±0.1	—	±1	—	±1	µA
3-State Leakage Current I_{OZ}	V_{IH} or V_{IL} $V_O =$ V_{CC} or GND		5.5	—	±0.5	—	±5	—	±10	µA
Quiescent Supply Current, MSI I_{CC}	V_{CC} or GND	0	5.5	—	8	—	80	—	160	µA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.
*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

STATIC ELECTRICAL CHARACTERISTICS: ACT Series

CHARACTERISTICS	TEST CONDITIONS		V_{CC} (V)	AMBIENT TEMPERATURE (T_A) - °C						UNITS
				+25		-40 to +85		-55 to +125		
	V_I (V)	I_O (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage V_{IH}			4.5 to 5.5	2	—	2	—	2	—	V
Low-Level Input Voltage V_{IL}			4.5 to 5.5	—	0.8	—	0.8	—	0.8	V
High-Level Output Voltage V_{OH}	V_{IH} or V_{IL} #, *	-0.05	4.5	4.4	—	4.4	—	4.4	—	V
		-24	4.5	3.94	—	3.8	—	3.7	—	
		-75	5.5	—	—	3.85	—	—	—	
		-50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage V_{OL}	V_{IH} or V_{IL} #, *	0.05	4.5	—	0.1	—	0.1	—	0.1	V
		24	4.5	—	0.36	—	0.44	—	0.5	
		75	5.5	—	—	—	1.65	—	—	
		50	5.5	—	—	—	—	—	1.65	
Input Leakage Current I_I	V_{CC} or GND		5.5	—	±0.1	—	±1	—	±1	µA
3-State Leakage Current I_{OZ}	V_{IH} or V_{IL} V_O = V_{CC} or GND		5.5	—	±0.5	—	±5	—	±10	µA
Quiescent Supply Current, MSI I_{CC}	V_{CC} or GND	0	5.5	—	8	—	80	—	160	µA
Additional Quiescent Supply Current per Input Pin TTL Inputs High ΔI_{CC} 1 Unit Load	V_{CC}-2.1		4.5 to 5.5	—	2.4	—	2.8	—	3	mA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

ACT INPUT LOADING TABLE

INPUT	UNIT LOAD*
An, Bn	0.83
$\overline{OE}_{BA}$	0.64
OE_{AB}	0.15

*Unit load is ΔI_{CC} limit specified in Static Characteristics Chart, e.g., 2.4 mA max. @ 25°C.

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CD54/74AC623
CD54/74ACT623

SWITCHING CHARACTERISTICS: AC Series; t_r, t_f = 3 ns, C_L = 50 pF

CHARACTERISTICS	SYMBOL	V_{CC} (V)	AMBIENT TEMPERATURE (T_A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Data to Output	t_{PLH} t_{PHL}	1.5 3.3* 5†	— 3.5 2.5	108 12.2 8.7	— 3.4 2.4	120 13.4 9.6	ns
Output Disable to Output	t_{PLZ} t_{PHZ}	1.5 3.3 5	— 4.8 3.5	153 17.1 12.2	— 4.7 3.4	168 18.8 13.4	ns
Output Enable to Output	t_{PZL} t_{PZH}	1.5 3.3 5	— 4.8 3.5	153 17.1 12.2	— 4.7 3.4	168 18.8 13.4	ns
Power Dissipation Capacitance	C_{PD}§	—	66 Typ.		66 Typ.		pF
Min. (Valley) V_{OH} During Switching of Other Outputs (Output Under Test Not Switching)	V_{OHV} See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) V_{OL} During Switching of Other Outputs (Output Under Test Not Switching)	V_{OLP} See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C_I	—	—	10	—	10	pF
3-State Output Capacitance	C_O	—	—	15	—	15	pF

SWITCHING CHARACTERISTICS: ACT Series; t_r, t_f = 3 ns, C_L = 50 pF

CHARACTERISTICS	SYMBOL	V_{CC} (V)	AMBIENT TEMPERATURE (T_A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Data to Output	t_{PLH} t_{PHL}	5†	2.7	9.6	2.7	10.6	ns
Output Disable to Output	t_{PLZ} t_{PHZ}	5	3.7	13.1	3.6	14.4	ns
Output Enable to Output	t_{PZH} t_{PZL}	5	3.7	13.1	3.6	14.4	ns
Power Dissipation Capacitance	C_{PD}§	—	66 Typ.		66 Typ.		pF
Min. (Valley) V_{OH} During Switching of Other Outputs (Output Under Test Not Switching)	V_{OHV} See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) V_{OL} During Switching of Other Outputs (Output Under Test Not Switching)	V_{OLP} See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C_I	—	—	10	—	10	pF
3-State Output Capacitance	C_O	—	—	15	—	15	pF

*3.3 V: min. is @ 3.6 V
     max. is @ 3 V

†5 V: min. is @ 5.5 V
     max. is @ 4.5 V

§C_{PD} is used to determine the dynamic power consumption, per channel.
For AC series: $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$
For ACT series: $P_D = V_{CC}^2 f_i (C_{PD} + C_L) + V_{CC} \Delta I_{CC}$ where f_i = input frequency
                                                C_L = output load capacitance
 V_{CC} = supply voltage.

PARAMETER MEASUREMENT INFORMATION
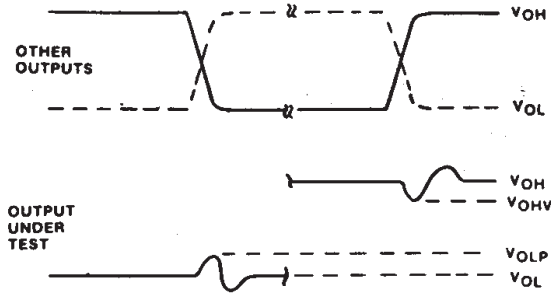
NOTES:
1. V_{OHV} AND V_{OLP} ARE MEASURED WITH RESPECT TO A GROUND REFERENCE NEAR THE OUTPUT UNDER TEST.
2. INPUT PULSES HAVE THE FOLLOWING CHARACTERISTICS: PRR ≤ 1 MHz, t_r = 3 ns, t_f = 3 ns, SKEW 1 ns.
3. R.F. FIXTURE WITH 700-MHz DESIGN RULES REQUIRED. IC SHOULD BE SOLDERED INTO TEST BOARD AND BYPASSED WITH 0.1 µF CAPACITOR. SCOPE AND PROBES REQUIRE 700-MHz BANDWIDTH.

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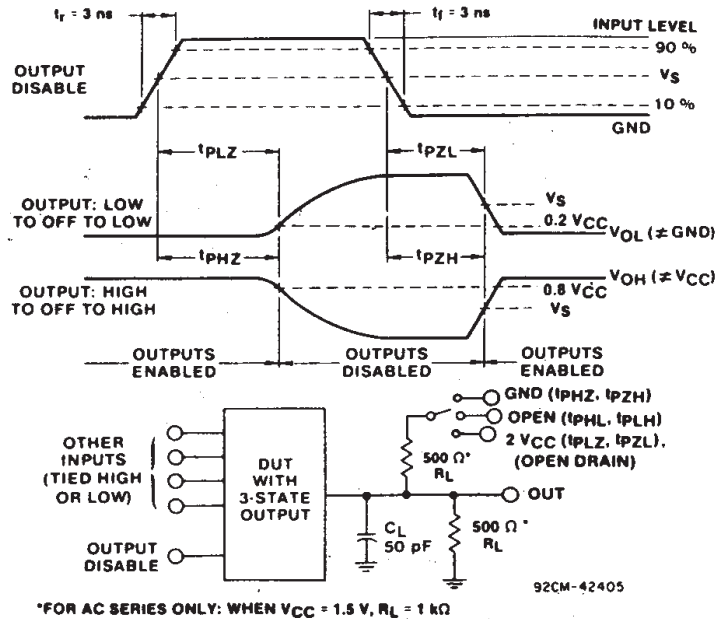
Fig. 1 - Simultaneous switching transient waveforms.

*FOR AC SERIES ONLY: WHEN V_{CC} = 1.5 V, R_L = 1 kΩ

92CM-42405

Fig. 2 - Three-state propagation delay times and test circuit.

*FOR AC SERIES ONLY: WHEN V_{CC} = 1.5 V, R_L = 1 kΩ

92CS-42389

92CS-42587
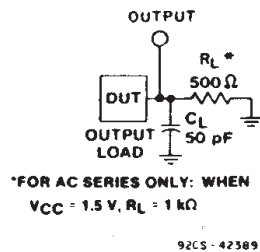
Fig. 3 - Propagation delay times and test circuit.

	CD54/74AC	CD54/74ACT
Input Level	V_{CC}	3 V
Input Switching Voltage, V_S	0.5 V_{CC}	1.5 V
Output Switching Voltage, V_S	0.5 V_{CC}	0.5 V_{CC}

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PACKAGE OPTION ADDENDUM

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD54ACT623F3A	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD54ACT623F3A	Samples
CD74AC623E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC623E	Samples
CD74AC623M	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC623M	Samples
CD74ACT623M96	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT623M	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD54ACT623, CD74ACT623 :

- Catalog: CD74ACT623

- Military: CD54ACT623

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

- Military - QML certified for Military and Defense Applications

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14-Jul-2012

PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74ACT623M96	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74ACT623M96	SOIC	DW	20	2000	367.0	367.0	45.0

DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	——	——	——	——
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

B

14   8

0.065 (1,65)
0.045 (1,14)

C

1   7

0.005 (0,13) MIN

0.060 (1,52)
0.015 (0,38)

0.200 (5,08) MAX

Seating Plane

0.130 (3,30) MIN

0.026 (0,66)
0.014 (0,36)

0.100 (2,54)

A

0°—15°

0.014 (0,36)
0.008 (0,20)

4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         C. This package is hermetically sealed with a ceramic lid using glass frit.
         D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
         E. Falls within MIL STD 1835 GDIP1—T14, GDIP1—T16, GDIP1—T18 and GDIP1—T20.

N (R−PDIP−T**)   PLASTIC DUAL−IN−LINE PACKAGE

16 PINS SHOWN

PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS−001 VARIATION	AA	BB	AC	AD

A

16   9

0.260 (6,60)
0.240 (6,10)

1   8

0.070 (1,78)
0.045 (1,14) ⬦D

0.045 (1,14) ⬦D
0.030 (0,76)

0.020 (0,51) MIN

0.325 (8,26)
0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.010 (0,25) NOM

0.100 (2,54)

0.430 (10,92) MAX

0.021 (0,53)
0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

14/18 Pin Only
20 Pin vendor option ⬦D

4040049/E 12/2002

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         ⬦C Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
         ⬦D The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R−PDSO−G20)   PLASTIC SMALL OUTLINE

0.512 (13,00)
0.496 (12,60)

20   11

0.419 (10,63)
0.393 (9,97)

0.299 (7,60)
0.291 (7,40)

1   10

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.104 (2,65) Max

0.012 (0,30)
0.004 (0,10)

0.013 (0,33)
0.008 (0,20)

Gauge Plane

0.004 (0,10)

Seating Plane

0.010 (0,25)   0°−8°

0.050 (1,27)
0.016 (0,40)

4040000−4/G 01/11

NOTES: A.   All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M−1994.
         B.   This drawing is subject to change without notice.
         C.   Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
         D.   Falls within JEDEC MS−013 variation AC.

IMPORTANT NOTICE

Products		Applications	
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Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
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